

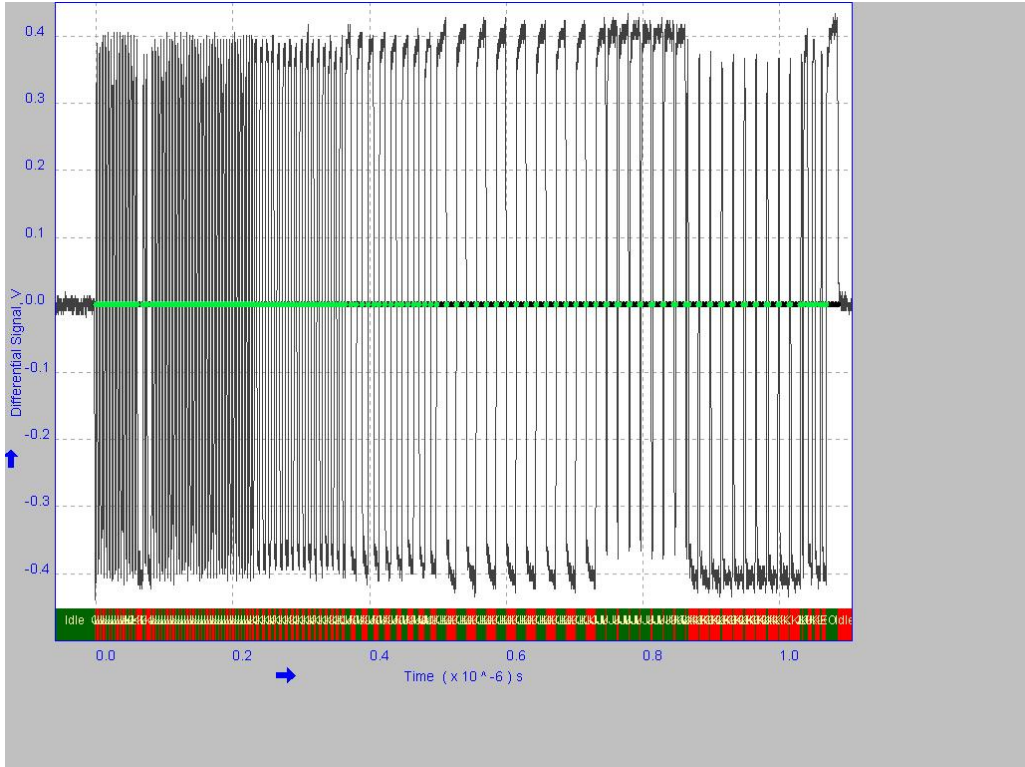
# Signal Quality Test Results in Tek format

**Device ID:** hs\_001

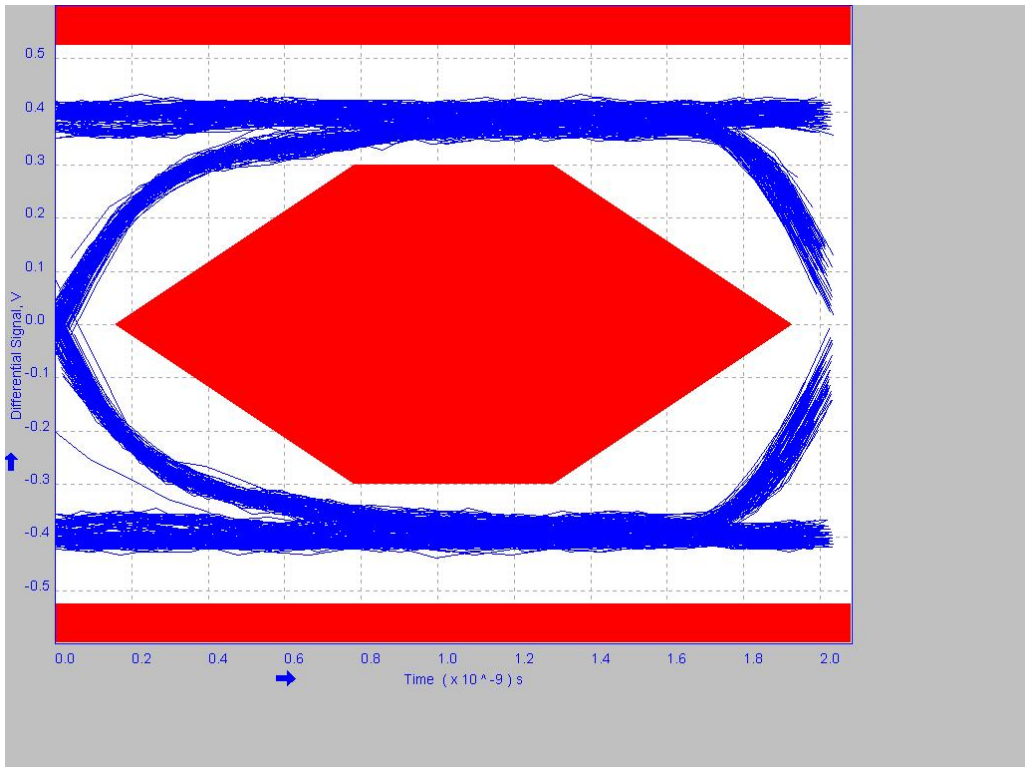
**Device Description:** High Speed, Near End Device, Up Stream Testing, Tier 1, Dummy Device.

**Date:** Fri Apr 04 14:03:38 CST 2014

**Overall Result:** Pass\*



Waveform Plot



## Eye Diagram

Results based on USB-IF / Waiver Limits :

Measurement Name	Minimum	Maximum	Mean	pk-pk	Standard Deviation	RMS	Population	Status
Monotonic Property	-	-	-	-	-	-	0	Pass
Eye Diagram Test	-	-	-	-	-	-	-	Pass
Signal Rate	470.2690Mbps	487.1768Mbps	480.0278Mbps	0.0000bps	2.253044Mbps	479.7777Mbps	512	Pass
EOP Width	-	-	16.57870ns	-	-	-	1	Pass
EOP Width (Bits)	-	-	7.958238	-	-	-	1	Pass
Falling Edge Rate	1.138013kV/us	1.538662kV/us	1.325134kV/us	400.6486 V/us	75.52521 V/us	1.327265kV/us	107	Pass
Rising Edge Rate	1.157605kV/us	1.415730kV/us	1.293416kV/us	258.1257 V/us	71.48793 V/us	1.295372kV/us	108	Pass

Monotonicity test is performed on the test limits of 15.0% and 85.0%.

Additional Information :

- Consecutive Jitter range : -52.83ps to 59.21ps RMS Jitter 21.30ps
- KJ Paired Jitter range : -42.46ps to 49.83ps RMS Jitter 14.65ps
- JK Paired Jitter range : -45.11ps to 64.10ps RMS Jitter 15.39ps
- Rising Edge Rate:1.293416kV/us (Equivalent Rise Time = 494.81 ps)
- Falling Edge Rate:1.325134kV/us (Equivalent Fall Time = 482.97 ps)

\*The Overall Result for this test is **Pass**, because one or more individual status of the measurements is **Pass**. For this test, the recommended configuration for USB2 testing (as per USB-IF) is on Tier 1.



TDSUSB2 software version: 3.1.1 Build 2

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